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To the Honorable Commissioner of

102695881

... original documents or copy thereof.

1. Name of conveying party(ies):
YASUI, NAOKI
WATANABE, SEIICHI
SUMIYA, MASAHIRO
TAMURA, HITOSHI

3-9-04

2. Name and address of receiving party(ies)
Name: **HITACHI HIGH-TECHNOLOGIES CORPORATION**

22859 U.S. PTO
10795353



Additional name(s) of conveying party(ies) attached? Yes No

Street Address: **1-24-14, Nishi Shimbashi, Minato-ku, Tokyo 105-8717, Japan**

3. Nature of conveyance:

- Assignment
- Security Agreement
- Other _____
- Merger
- Change of Name

City: _____ State: _____ Zip: _____

Execution Date: **March 1, 1, 1, 2004.**

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: **March 1, 1, 1, 2004.**

A. Patent Application No.(s)

10795353

B. Patent Registration No.(s)

Additional number(s) attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Antonelli, Terry, Stout & Kraus, LLP**

Internal Address:

**1300 North Seventeenth Street
Suite 1800
Arlington, VA 22209
USA**

City: _____ State: _____ Zip: _____

6. Total number of applications and patents involved **1**

7. Total fee (37 CFR 3.41)..... **\$40.00**

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Melvin Kraus, Reg# 22,466

Name of Person Signing

Melvin Kraus
Signature

03/09/2004

Date

Total number of pages including cover sheet, attachments, and document: **2**

Mail documents to be recorded with required cover sheet information to:
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Washington, D.C. 20231

03/11/2004 LWONDIM1 00000055 10795353

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ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 1-24-14, Nishi Shimbashi, Minato-ku, Tokyo 105-8717, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

PLASMA PROCESSING APPARATUS HAVING HIGH FREQUENCY POWER SOURCE WITH SAG COMPENSATION FUNCTION AND PLASMA PROCESSING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>YASUI, Naoki</u> <u>Naoki Yasui</u>	<u>2004. 03. 01</u>
2) <u>WATANABE, Seiichi</u> <u>Seiichi Watanabe</u>	<u>2004. 03. 01</u>
3) <u>SUMIYA, Masahiro</u> <u>Masahiro Sumiya</u>	<u>2004. 03. 01</u>
4) <u>TAMURA, Hitoshi</u> <u>Hitoshi Tamura</u>	<u>2004. 03. 01</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____